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**Low-voltage switchgear and controlgear – Controller-device interfaces (CDIs) –
Part 3: DeviceNet**

**Appareillage à basse tension – Interfaces appareil de commande-appareil (CDI) –
Partie 3: DeviceNet**



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Part 3: DeviceNet**

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**LOW-VOLTAGE SWITCHGEAR AND CONTROLGEAR –
CONTROLLER-DEVICE INTERFACES (CDIs) –****Part 3: DeviceNet****FOREWORD**

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International Standard IEC 62026-3 has been prepared by subcommittee 121A: Low-voltage switchgear and controlgear, of IEC technical committee 121: Switchgear and controlgear and their assemblies for low voltage.

This third edition of IEC 62026-3 cancels and replaces the second edition published in 2008. This third edition constitutes a technical revision.

The main changes with respect to the previous edition are the followings:

- specification of group 4 messages (5.1.2);
- clarifications on messaging protocol (5.2);
- addition of I/O multicast poll messages (5.5.2 and 5.5.8);
- clarifications on slave behaviour (5.5.4 and 5.5.9);
- clarifications on physical layer (transceiver) in 5.7;

- miscellaneous corrections/clarifications on cable (8.2);
- clarifications on EMC testing (9.2.10) and logical testing (9.3).

The text of this standard is based on the following documents:

FDIS	Report on voting
17B/1814/FDIS	121A/18/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 62026, under the general title *Low-voltage switchgear and controlgear – Controller-device interfaces (CDIs)*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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INTRODUCTION

DeviceNet™¹ is intended for use in, but is not limited to, industrial automation applications. These applications may include devices such as limit switches, proximity sensors, electro-pneumatic valves, relays, motor starters, operator interface panels, analogue inputs, analogue outputs and controllers.

¹ DeviceNet™ is a trade name of ODVA, Inc. This information is given for the convenience of users of this International Standard and does not constitute an endorsement by IEC of the trademark holder or any of its products. Compliance to this standard does not require use of the trade name DeviceNet™. Use of the trade name DeviceNet™ requires permission of ODVA, Inc.

LOW-VOLTAGE SWITCHGEAR AND CONTROLGEAR – CONTROLLER-DEVICE INTERFACES (CDIs) –

Part 3: DeviceNet

1 Scope

This part of IEC 62026 specifies an interface system between single or multiple controllers, and control circuit devices or switching elements. The interface system uses two conductor pairs within one cable – one of these pairs provides a differential communication medium and the other pair provides power to the devices. This part establishes requirements for the interoperability of components with such interfaces.

This part of IEC 62026 specifies the following particular requirements for DeviceNet:

- requirements for interfaces between controllers and switching elements;
- normal service conditions for devices;
- constructional and performance requirements;
- tests to verify conformance to requirements.

These particular requirements apply in addition to the general requirements of IEC 62026-1.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60529:1989, *Degrees of protection provided by enclosures (IP Code)*
IEC 60529:1989/AMD 1:1999
IEC 60529:1989/AMD 2:2013

IEC 60947-5-2:2007, *Low-voltage switchgear and controlgear – Part 5-2: Control circuit devices and switching elements – Proximity switches*
IEC 60947-5-2:2007/AMD 1:2012

IEC 61000-4-2:2008, *Electromagnetic compatibility (EMC) – Part 4-2: Testing and measurement techniques – Electrostatic discharge immunity test*

IEC 61000-4-3:2006, *Electromagnetic compatibility (EMC) – Part 4-3: Testing and measurement techniques – Radiated, radio-frequency, electromagnetic field immunity test*
IEC 61000-4-3:2006/AMD 1:2007
IEC 61000-4-3:2006/AMD 2:2010

IEC 61000-4-4:2012, *Electromagnetic compatibility (EMC) – Part 4-4: Testing and measurement techniques – Electrical fast transient/burst immunity test*

IEC 61000-4-5:2005, *Electromagnetic compatibility (EMC) – Part 4-5: Testing and measurement techniques – Surge immunity test*

IEC 61000-4-6:2013, *Electromagnetic compatibility (EMC) – Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields*

IEC 61158-4-2:2014, *Industrial communication networks – Fieldbus specifications – Part 4-2: Data-link layer protocol specification – Type 2 elements*

IEC 61158-5-2:2014, *Industrial communication networks – Fieldbus specifications – Part 5-2: Application layer service definition – Type 2 elements*

IEC 61158-6-2:2014, *Industrial communication networks – Fieldbus specifications – Part 6-2: Application layer protocol specification – Type 2 elements*

IEC 61784-3-2, *Industrial communication networks – Profiles – Part 3-2: Functional safety fieldbuses – Additional specifications for CPF 2*

IEC 62026-1:2007, *Low-voltage switchgear and controlgear – Controller-device interfaces (CDIs) – Part 1: General rules*

CISPR 11:2009, *Industrial, scientific and medical equipment – Radio-frequency disturbance characteristics – Limits and methods of measurement*
CISPR 11:2009/AMD 1:2010

ISO 11898-1:2003, *Road vehicles – Controller area network (CAN) – Part 1: Data link layer and physical signalling*

ISO 11898-2:2003, *Road vehicles – Controller area network (CAN) – Part 2: High-speed medium access unit*

ANSI B93.55M-1981 (R1988), *Hydraulic Fluid Power – Solenoid Piloted Industrial Valves – Interface Dimensions for Electrical Connectors*

ASTM D 4566-942, *Standard Test Methods for Electrical Performance Properties of Insulations and Jackets for Telecommunications Wire and Cable*

3 Terms, definitions, symbols and abbreviated terms

For the purposes of this document, the terms, definitions, symbols and abbreviations given in IEC 62026-1 as well as the following apply.

3.1 Terms and definitions

3.1.1

acknowledged fragmentation

fragmentation performed on an explicit message, in which the transmission of a fragment from the transmitting object is followed by the transmission of an acknowledgement by the receiving object

Note 1 to entry: The reception of each fragment is acknowledged by the receiving object.

² A newer version of this document exists (ASTM D4566-08e1), however the listed revision applies for this standard